

Amendments to the Specification:

Please replace the fourth paragraph on page 1 with the following amended paragraph:

The task of the invention is to produce an electronic component for which the adhesion of solder splash or solder itself to surfaces not intended for soldering is prevented to the greatest extent possible. In particular, such a surface-mountable component is to be developed that may be packed in belts and subsequently used by conventional pick-and-place processes of [[SMT¹]] SMD technology.

Please delete footnote 1 on the bottom of page 2.